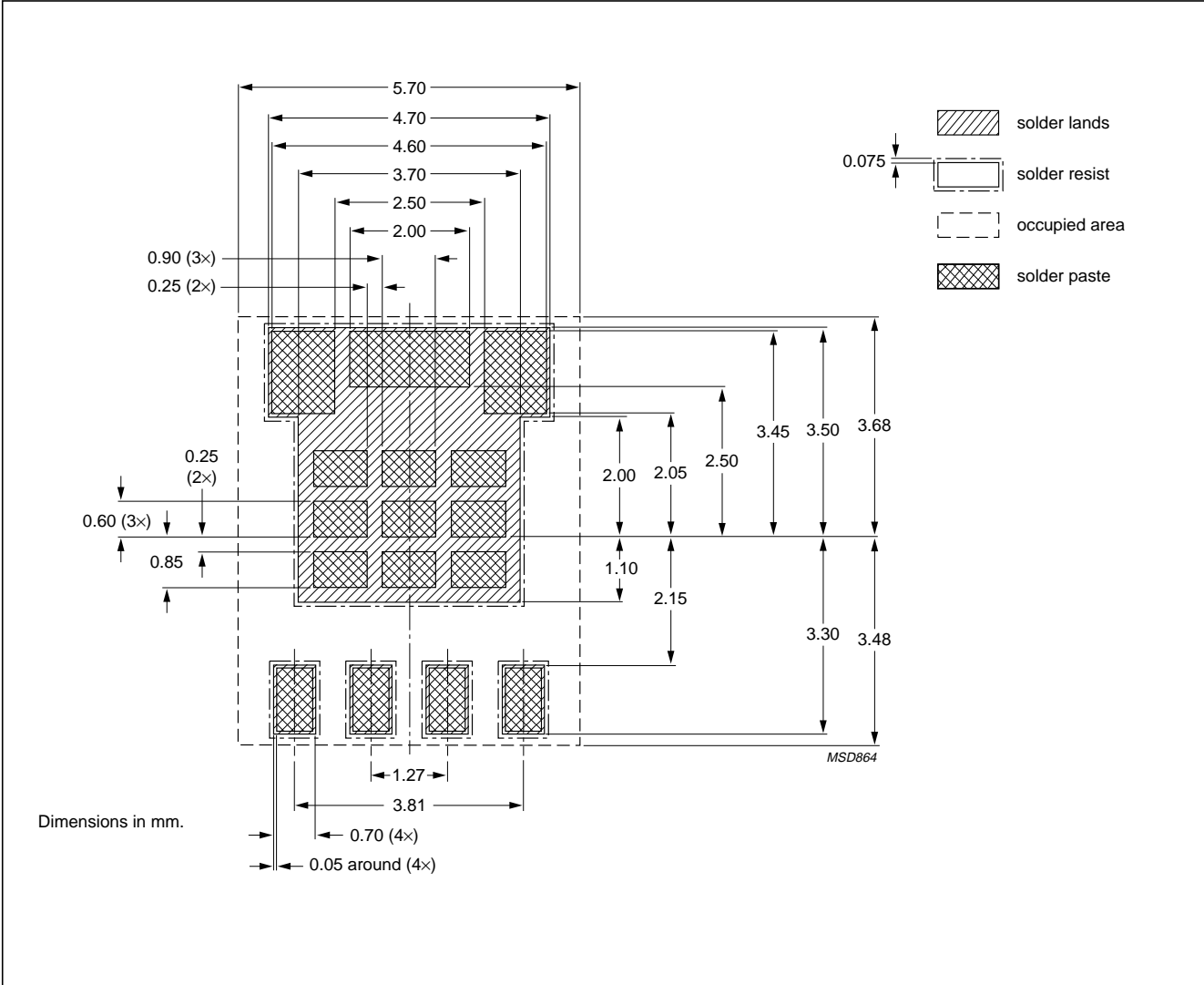
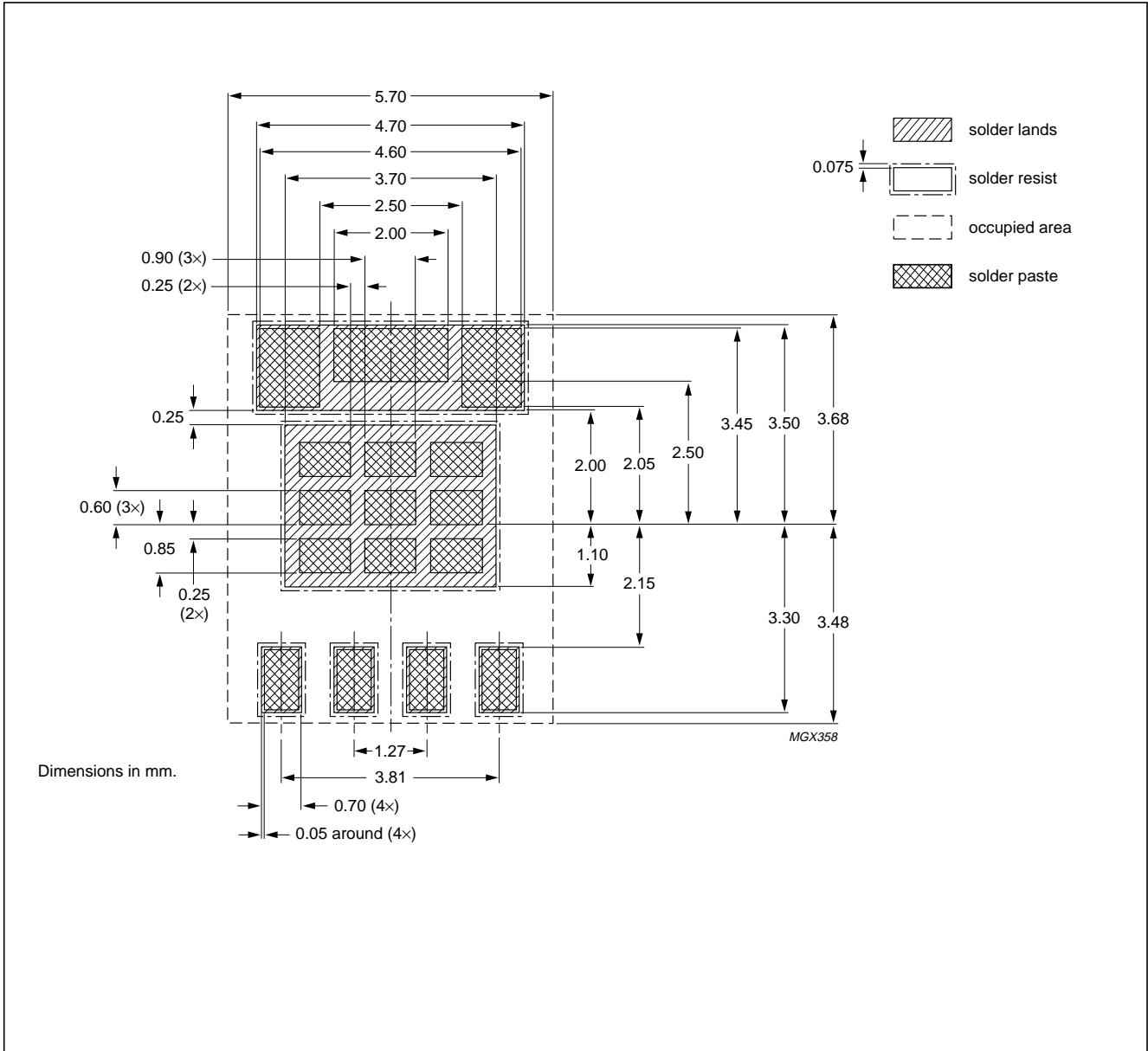


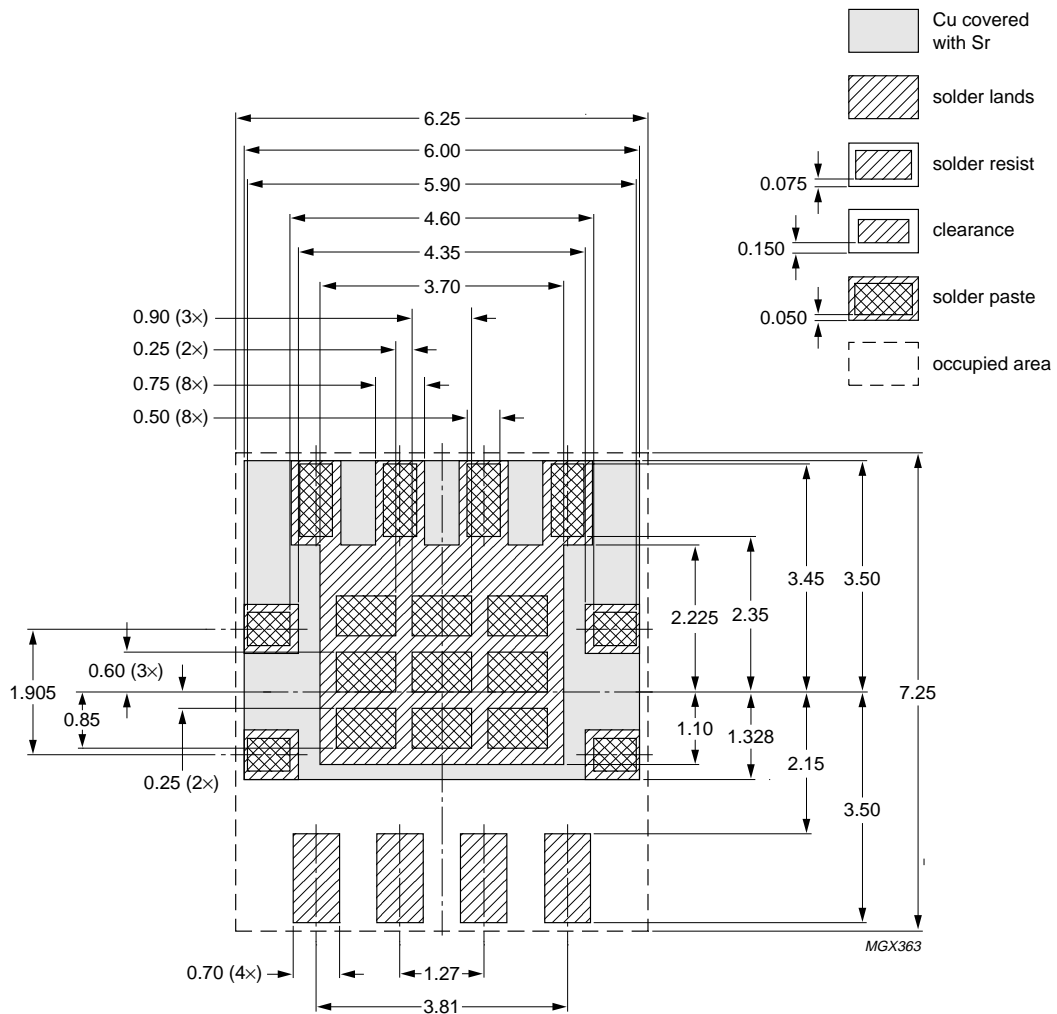
OPTIMIZED FOOTPRINT SOT669 (LF-PAK) (REFLOW SOLDERING) see also COMBI FOOTPRINTS next pages



COMBI FOOTPRINT LF-PAK and SO8 (REFLOW SOLDERING)

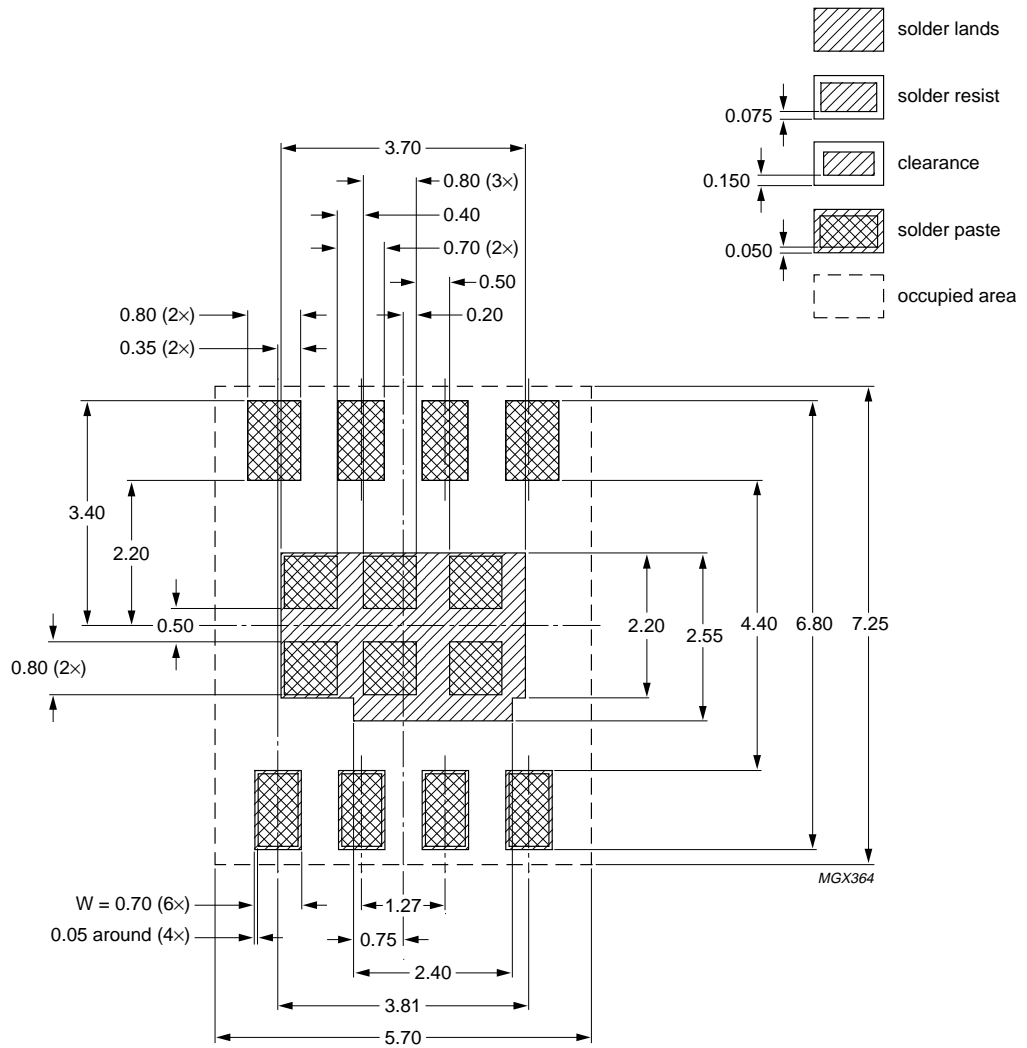


COMBI FOOTPRINT LF-PAK and QL-PAK (SOT685-1) (REFLOW SOLDERING)



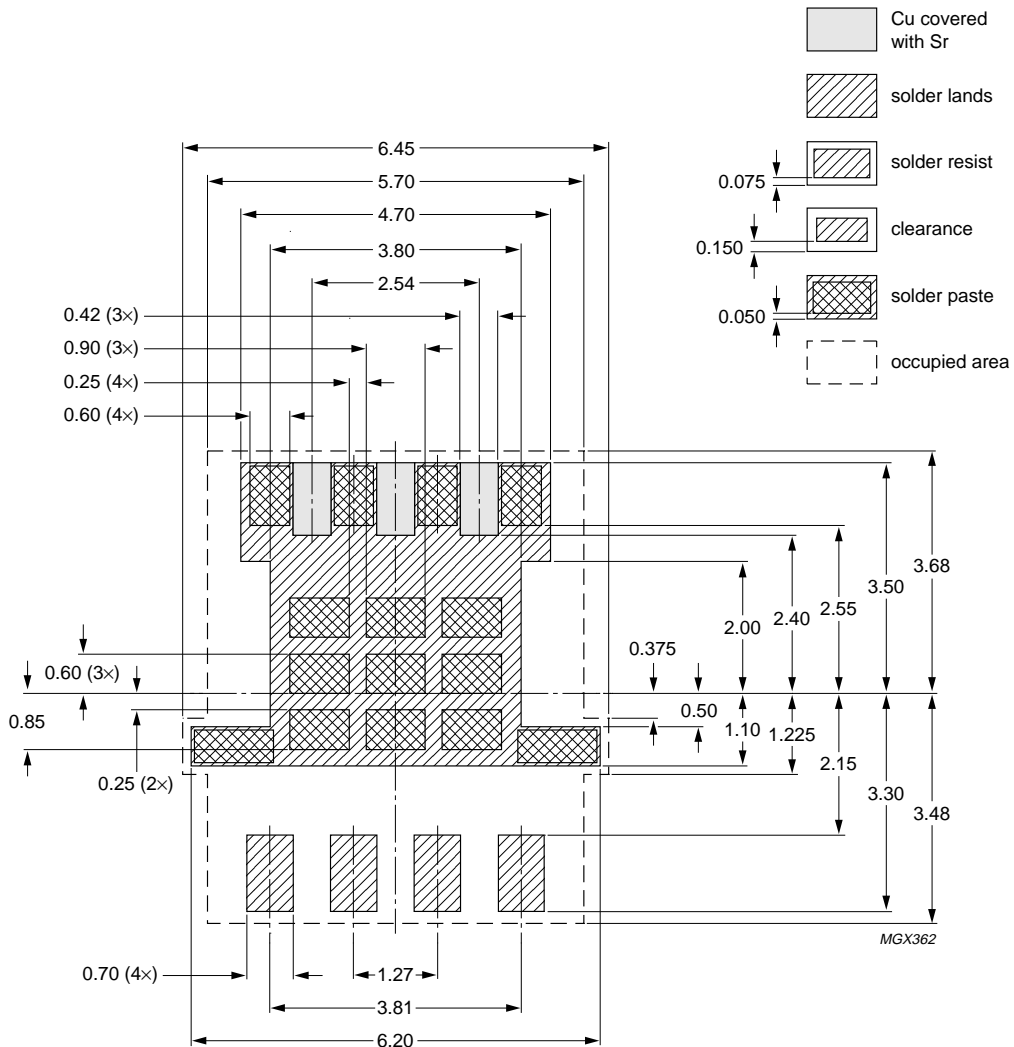
Dimensions in mm.

COMBI FOOTPRINT LF-PAK and BOTTOMLESS SO8 (REFLOW SOLDERING)



Only valid for Fairchild FDS7064A or chip 2.36 x 2.36 mm. Footprints are available on request (necessary if drain terminal on bottomless SO8 deviates from FDS7064A).

COMBI FOOTPRINT LF-PAK and POWER PAK SO8 (REFLOW SOLDERING)



Dimensions in mm.